

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An optical device, comprising:
  - a first semiconductor substrate having an optical part and a first pad the optical part being fixedly formed on a surface of the first semiconductor substrate;
  - a second semiconductor substrate stacked under the first semiconductor, the second semiconductor substrate having an integrated circuit and a second pad being pad, stacked under the first semiconductor; the second semiconductor substrate being directly adhered via an adhesive layer to the first semiconductor substrate with no gap other than the adhesive layer between the first and second semiconductor substrates;
  - a through-hole continuously extending through the first and the second semiconductor substrate; and
  - a conductive part disposed on an inside of the through-hole.
2. (Original) The optical device according to claim 1,
  - the optical part being formed on a side of a surface of the first semiconductor substrate opposite to the second semiconductor substrate.
3. (Original) The optical device according to claim 1,
  - the integrated circuit being formed on a side of a surface of the second semiconductor substrate opposite to the first semiconductor substrate.
4. (Original) The optical device according to any one of claim 1,
  - the through-hole being formed so as to extend through at least one of the first and the second pad.
5. (Original) The optical device according to any one of claim 1, further comprising:

an insulating layer formed on the inside of the through-hole, the conductive part being disposed on the insulating layer.

6. (Original) The optical device according to claim 1, the conductive part having an electrical connection on a side of a surface of the second semiconductor substrate opposite to the first semiconductor substrate.

7. (Original) The optical device according to claim 6, a pitch of the electrical connection being larger than a pitch of the second pad.

8. (Original) The optical device according to claim 6, further comprising:  
an external terminal provided on the electrical connection.

9. (Original) The optical device according to claim 6, further comprising:  
a resin layer formed on the side of the surface of the second semiconductor substrate opposite to the first semiconductor substrate, the electrical connection being formed on the resin layer.

10. (Original) The optical device according to claim 9, the resin layer being formed in an area overlapping the optical part.

11. (Original) The optical device according to claim 1, further comprising:  
an intermediate layer interposed between the first and the second semiconductor substrate.

12. (Original) The optical device according to claim 11, the intermediate layer including a metallic layer formed in an area overlapping the optical part.

13. (Original) The optical device according to claim 1, the optical part having a plurality of light-receiving elements.

14. (Original) The optical device according to claim 13,  
each of the plurality of light-receiving elements being arrayed for image sensing.

15. (Original) An optical module, further comprising:  
an optical device according to claim 1;  
a wiring substrate facing the second semiconductor substrate; and  
a substrate member holding a lens mounted on the wiring substrate and being  
provided above the first semiconductor substrate.
- 16-22. (Canceled)
23. (Original) An electronic apparatus, comprising:  
the optical device according to claim 1.
- 24-30. (Canceled)
31. (New) An optical device, comprising:  
a first semiconductor substrate having an optical part and a first pad the optical  
part being fixedly formed on a surface of the first semiconductor substrate;  
a second semiconductor substrate having an integrated circuit and a second  
pad being stacked under the first semiconductor;  
a through-hole continuously extending through the first and the second  
semiconductor substrate and continuously extending from the first semiconductor substrate to  
the second semiconductor substrate; and  
a conductive part disposed on an inside of the through-hole.